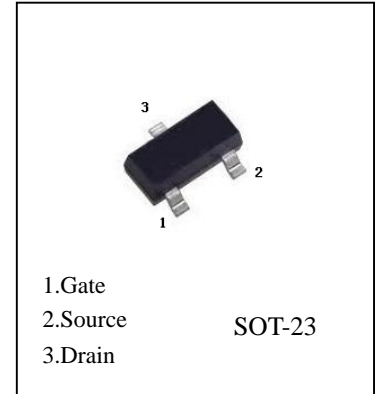
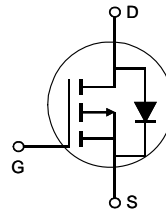


FEATURES

- The AO3403 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. This device is suitable for use as a load switch or in PWM applications.

**AO3403**

P-Channel MOSFET



Absolute Maximum Ratings (TA=25°C, unless otherwise noted)

| Parameter                              | Symbol         | Maximum                | Unit |
|--|----------------|------------------------|------|
| Drain-Source Voltage                   | $V_{DS}$       | -30                    | V    |
| Gate-Source Voltage                    | $V_{GS}$       | ±12                    | V    |
| Continuous Drain Current               | $I_D$          | $T_A=25^\circ\text{C}$ | -2.6 |
|  |                | $T_A=70^\circ\text{C}$ | -2.2 |
| Pulsed Drain Current <sup>C</sup>      | $I_{DM}$       | -13                    | A    |
| Power Dissipation <sup>B</sup>         | $P_D$          | $T_A=25^\circ\text{C}$ | 1.4  |
|  |                | $T_A=70^\circ\text{C}$ | 0.9  |
| Junction and Storage Temperature Range | $T_J, T_{STG}$ | -55 to 150             | °C   |

Thermal Characteristics

| Parameter                                  | Symbol   | Typ          | Max | Unit |      |
|--|----------|--------------|-----|------|------|
| Maximum Junction-to-Ambient <sup>A</sup>   | $R_{JA}$ | t = 10s      | 70  | 90   | °C/W |
| Maximum Junction-to-Ambient <sup>A,D</sup> |          | Steady-State | 100 | 125  | °C/W |
| Maximum Junction-to-Lead                   | $R_{JL}$ | Steady-State | 63  | 80   | °C/W |

**AO3403**

Electrical Characteristics (TA=25°C, unless otherwise noted)

| Symbol                      | Parameter                             | Conditions   | Min  | Typ   | Max       | Unit |
|-----------------------------|---------------------------------------|--|------|-------|-----------|------|
| <b>STATIC PARAMETERS</b>    |                                       |  |      |       |           |      |
| $BV_{DSS}$                  | Drain-Source Breakdown Voltage        | $I_D=-250\text{ A}, V_{GS}=0V$                       | -30  |       |           | V    |
| $I_{DSS}$                   | Zero Gate Voltage Drain Current       | $V_{DS}=-30V, V_{GS}=0V$                             |      |       | -1        | uA   |
|                             |                                       | $T_J=55^\circ C$                                     |      |       | -5        |      |
| $I_{GSS}$                   | Gate-Body leakage current             | $V_{DS}=0V, V_{GS}=\pm 12V$                          |      |       | $\pm 100$ | nA   |
| $V_{GS(th)}$                | Gate Threshold Voltage                | $V_{DS}=V_{GS}, I_D=-250\text{ A}$                   | -0.6 | -1    | -1.4      | V    |
| $I_{D(ON)}$                 | On state drain current                | $V_{GS}=-10V, V_{DS}=-5V$                            | -13  |       |           | A    |
| $R_{DS(on)}$                | Static Drain-Source On-Resistance     | $V_{GS}=-10V, I_D=-2.6A$                             |      | 88    | 115       | m    |
|                             |                                       | $T_J=125^\circ C$                                    |      | 143   | 200       |      |
|                             |                                       | $V_{GS}=-4.5V, I_D=-2A$                              |      | 103   | 150       | m    |
|                             |                                       | $V_{GS}=-2.5V, I_D=-1A$                              |      | 139   | 200       | m    |
| $g_{FS}$                    | Forward Transconductance              | $V_{DS}=-5V, I_D=-2.6A$                              |      | 8     |           | S    |
| $V_{SD}$                    | Diode Forward Voltage                 | $I_S=-1A, V_{GS}=0V$                                 |      | -0.78 | -1        | V    |
| $I_S$                       | Maximum Body-Diode Continuous Current |  |      |       | -1.5      | A    |
| <b>DYNAMIC PARAMETERS</b>   |                                       |  |      |       |           |      |
| $C_{iss}$                   | Input Capacitance                     | $V_{GS}=0V, V_{DS}=-15V, f=1MHz$                     |      | 260   | 315       | pF   |
| $C_{oss}$                   | Output Capacitance                    |  |      | 37    |           | pF   |
| $C_{rss}$                   | Reverse Transfer Capacitance          |  |      | 20    |           | pF   |
| $R_g$                       | Gate resistance                       | $V_{GS}=0V, V_{DS}=0V, f=1MHz$                       | 4    | 8     | 12        |      |
| <b>SWITCHING PARAMETERS</b> |                                       |  |      |       |           |      |
| $Q_g(10V)$                  | Total Gate Charge                     | $V_{GS}=-10V, V_{DS}=-15V, I_D=-2.6A$                |      | 5.9   | 7.2       | nC   |
| $Q_g(4.5V)$                 | Total Gate Charge                     |  |      | 2.8   | 3.5       | nC   |
| $Q_{gs}$                    | Gate Source Charge                    |  |      | 0.7   |           | nC   |
| $Q_{gd}$                    | Gate Drain Charge                     |  |      | 1     |           | nC   |
| $t_{D(on)}$                 | Turn-On DelayTime                     | $V_{GS}=-10V, V_{DS}=-15V,$<br>$R_L=5.76, R_{GEN}=3$ |      | 6     |           | ns   |
| $t_r$                       | Turn-On Rise Time                     |  |      | 3.5   |           | ns   |
| $t_{D(off)}$                | Turn-Off DelayTime                    |  |      | 20    |           | ns   |
| $t_f$                       | Turn-Off Fall Time                    |  |      | 5     |           | ns   |
| $t_{rr}$                    | Body Diode Reverse Recovery Time      | $I_F=-2.6A, dI/dt=100A/\mu s$                        |      | 11.5  | 15        | ns   |
| $Q_{rr}$                    | Body Diode Reverse Recovery Charge    | $I_F=-2.6A, dI/dt=100A/\mu s$                        |      | 4.5   |           | nC   |

A. The value of  $R_{JA}$  is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ C$ . The value in any given application depends on the user's specific board design.

B. The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ C$ , using  $\leq 10s$  junction-to-ambient thermal resistance.

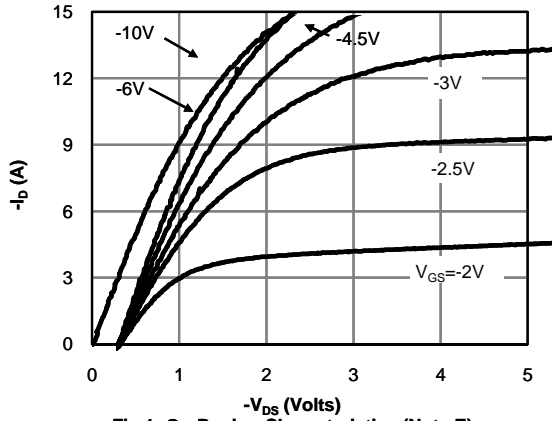
C. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^\circ C$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^\circ C$ .

D. The  $R_{JA}$  is the sum of the thermal impedance from junction to lead  $R_{JL}$  and lead to ambient.

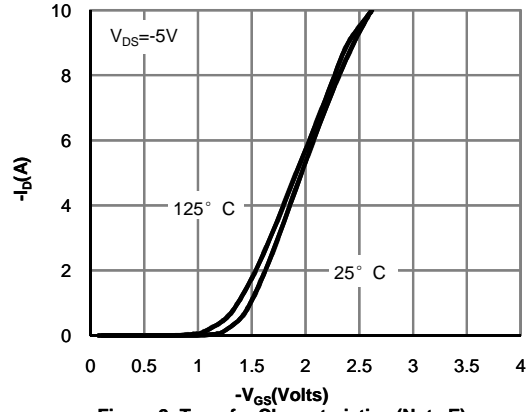
E. The static characteristics in Figures 1 to 6 are obtained using  $<300\mu s$  pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, assuming a maximum junction temperature of  $T_{J(MAX)}=150^\circ C$ . The SOA curve provides a single pulse rating.

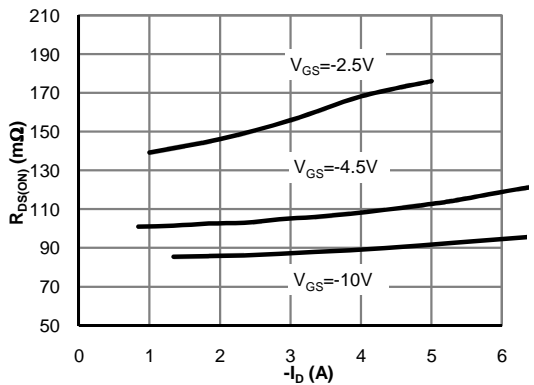
**AO3403** Typical Characteristics



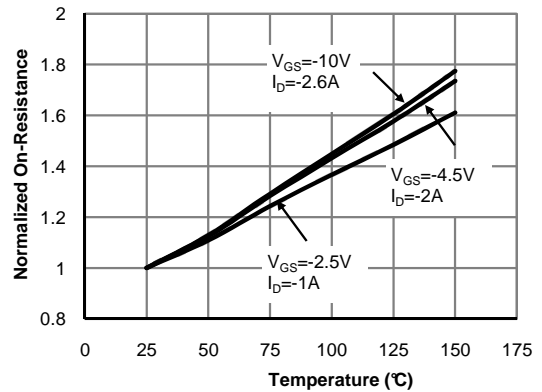
**Fig 1: On-Region Characteristics (Note E)**



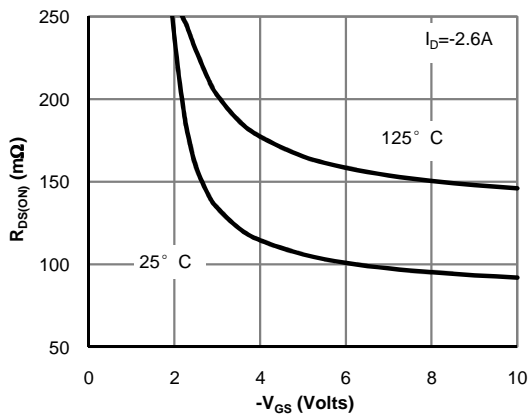
**Figure 2: Transfer Characteristics (Note E)**



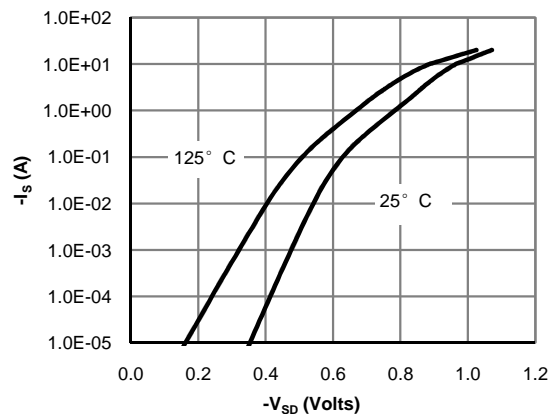
**Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)**



**Figure 4: On-Resistance vs. Junction Temperature (Note E)**



**Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)**



**Figure 6: Body-Diode Characteristics (Note E)**

**AO3403** Typical Characteristics

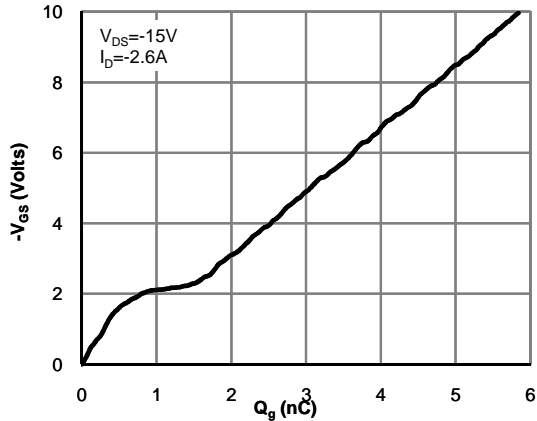


Figure 7: Gate-Charge Characteristics

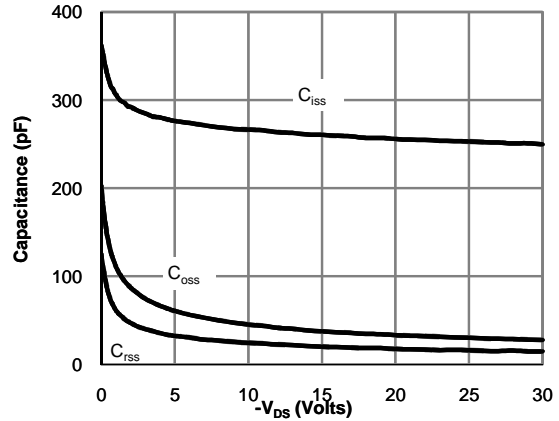


Figure 8: Capacitance Characteristics

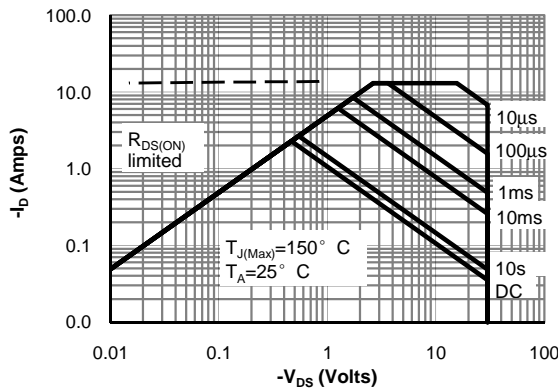


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

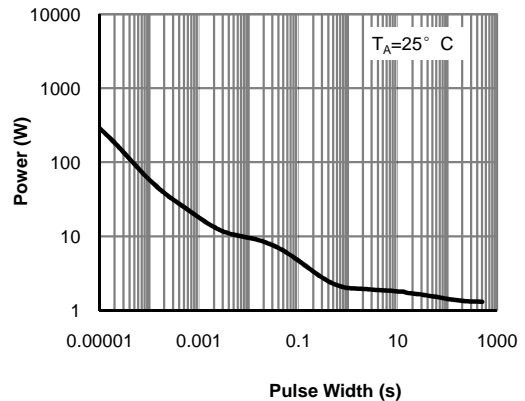


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

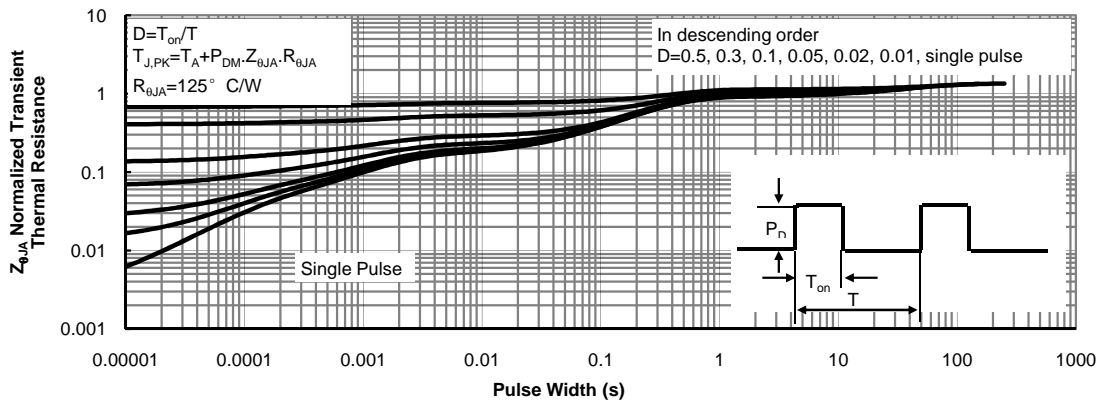


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)